



WW12D, WW08D

±1%, ±5%

Metal Foil low ohm power chip resistors

Size 1206 (1W), 0805 (1/2W)

Sensing Type

*Contents in this sheet are subject to change without prior notice.



FEATURE

- 1. Ultra low and stable TCR performance
- 2. High power rating and compact size
- 3. High reliability and stability
- 4. Reduced size of final equipment
- 5. RoHS compliant & Lead free

APPLICATION

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- Battery charger
- DC-DC power converter

DESCRIPTION

The resistors are constructed in a high grade low resistive metal foil which adhere on top of ceramic substrate body. The resistive layer is covered with a protective coat and printed a resistance marking code over it. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Lead free terminations.



Fig 1. Construction of Chip-R

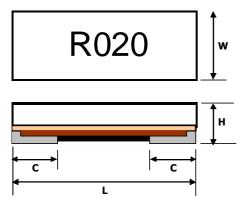
QUICK REFERENCE DATA

Item	General Specification		
Series No.	WW08D	WW12D	
Size code	0805 (2012) 1206 (3216)		
Resistance Tolerance	±5% , ±1%		
Resistance Range	20, 25, 30, 40, 50 mΩ	20, 25, 30, 40, 50 mΩ	
TCR (ppm/°C) +20 ~ 155°C	±100 ppm/°C		
Max. power at T _{amb} =70°C	1/2W	1W	
Max. Operation Current (DC or RMS)	5A, 4.4A, 4A, 3.5A, 3.1A	7A, 6.3A, 5.7A, 5A, 4.4A	
Climatic category (IEC 60068)	55/155/56		

Note : Max. Operation Current : So called RCWC (Rated Continuous Working Current) is determined by

 $RCWC = \sqrt{Rated Power / Resistance Value}$ listed above.

MECHANICAL DATA



Unit: mm

Туре	Size (inch)	Resistance	L (mm)	W (mm)	H (mm)	C (mm)
		20mΩ		1.6±0.15	0.55±0.10	1.0±0.25
		25mΩ			0.55±0.10	0.8±0.25
WW12D	1206	30mΩ	3.2±0.15		0.55±0.10	0.5±0.25
		40mΩ			0.50±0.10	0.8±0.25
		50mΩ			0.50±0.10	0.6±0.25
	0805	20mΩ	1.95±0.15	1.2±0.15	0.55±0.10	0.50±0.20
		25mΩ			0.55±0.10	0.35±0.20
WW08D		30mΩ			0.50±0.10	0.30±0.20
		40mΩ			0.50±0.10	0.55±0.20
		50mΩ			0.50±0.10	0.45±0.20



MARKING

Each resistor is marked with a four-digit code on the protective coating to designate the nominal resistance value.

Example:

 $\begin{aligned} \mathsf{R}020 &= 0.02\Omega \\ \mathsf{R}040 &= 0.04\Omega \end{aligned}$

FUNCTIONAL DESCRIPTION

Derating curve

The power that the resistor can dissipate depends on the operating temperature; see Fig.2

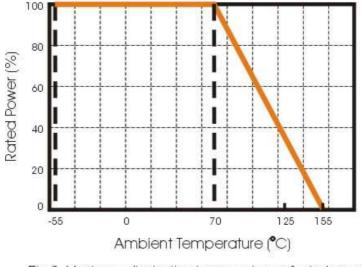


Fig.2 Maximum dissipation in percentage of rated power As a function of the ambient temperature

MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.



SOLDERING CONDITIONS

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds within lead-free solder bath. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig

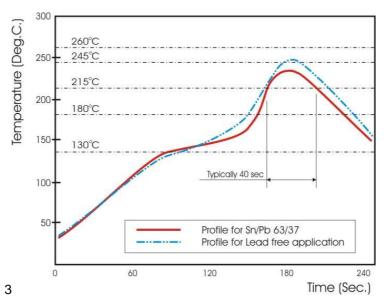


Fig 3. Infrared soldering profile for Chip Resistors WW12/08D

CATALOGUE NUMBERS

The resistors have a catalogue number starting with .

WW12	D	R020	F	т	L
Size code	Type code	Resistance code	Tolerance	Packaging code	Termination code
WW12 : 1206 WW08 : 0805	D : Metal foil	R is first digit followed by 3 significant digits. $0.020\Omega = R020$ $0.040\Omega = R040$	J :±5% F :±1%	T : 7" reeled in tape	L = Sn base (lead free)

Reeled tape packaging : 8mm width paper taping 5,000pcs per reel.



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Ne	Testitense	Table- 4(1)	Defermence requirements	
No.	Test items	Condition of test (JIS C 5201-1)	Performance requirements	
1	Visual examination	Sub–clause 4.4.1 Checked by visual examination.	As in 4.4.1 The marking shall be legible, a checked by visual examination.	
2	Dimension	Sub-clause 4.4.2	As specified in Table-3 of the specification.	
	Resistance	Resistance value shall be measured by mounting	As in 4.5.2	
		the substrate of the following condition.	The resistance value sh correspond with the rated resistan	
		Current terminal Voltage terminal Solder resist	taking into account the specif tolerance.	
		a: 2.9mm (2m Ω, 3mΩ, 4m Ω),		
		1.8mm (5m Ω)		
		Thickness of copper clad: 0.035mm		
		4-Terminal method		
		Measurement current: 1(A)		
		Note: The measuring apparatus corresponding to		
		DC Low-ohm Mater (1A) of AX-1152D for ADEX CORPORATION.		
3	Voltage proof	Sub-clause 4.7	No been kalawa an Anakarana	
		Method: 4.6.1.4(See Figure-5)	No breakdown or flash over	
		Test voltage: Alternating voltage with a peak value of 1.42 times the insulation voltage.		
		Duration: 60 s±5 s		
		Insulation resistance		
		Test voltage: Insulation voltage	R≥1GΩ	
		Duration: 1 min.		
4	Solderability	Sub-clause 4.17	As in 4.17.4.5	
		Without aging Flux: The resistors shall be immersed in a	The terminations shall be cover with a smooth and bright solo	
		non-activated soldering flux for 2 s.	coating.	
		Bath temperature: 235 °C±5 °C	- course	
		Immersion time: 2 s±0.5 s		
5	Mounting	Sub-clause 4.31		
		Substrate material: Epoxide woven glass		
	Overload	Test substrate: Figure-3		
	(in the mounted state)	Sub-clause 4.13		
	(in the mounted state)	The applied voltage shall be 2.5 times the rated voltage or the current corresponding to.		
		Duration: 2 S		
		Visual examination	No visible damage	
		Resistance	∆R≤±1%	
	Solvent resistance of the	Sub–clause 4.30	Legible marking	
	marking	Solvent: 2–propanol		
		Solvent temperature: 23 °C±5 °C		
		Method 1 Bubbing material: catter week		
		Rubbing material: cotton wool Without recovery		
		winout ecovery		

TEST & REQUIREMENTS



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		Table-4(2)	
No	Test items	Condition of test (JIS C 5201-1)	Performance requirements
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Devel strength of the and	Test substrate: Figure-4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 3 mm	10 4 10/
	Final measurements	Resistance	$\Delta R \leq \pm 1\%$
	Final measurements	Sub-clause 4.33.6	Ne visible democra
L		Visual examination	No visible damage
7	Resistance to soldering heat	Sub-clause 4.18	
		Solder temperature: 260 °C±5 °C	
		Immersion time: 10 s±0.5 s	A - 1- 440.2.4
		Visual examination	As in 4.18.3.4
		B 14	No sign of damage such as cracks.
	Component solvent	Resistance	∆R≤±1%
	Component solvent resistance	000 00000 4.20	
	resistance	Solvent: 2-propanol	
		Solvent temperature: 23 °C±5 °C Method 2	
		Recovery: 48 h Visual examination	No visible damage
		Resistance	AR<+1%
8	Mounting	Sub-clause 4.31	
ľ	mounting	Sub-clause 4.51 Substrate material: Epoxide woven glass	
		Test substrate: Figure-3	
	Adhesion	Sub-clause 4.32	
		Force 10N	
		Duration: 10 s±1 s	
		Visual examination	No visible damage
	Rapid change temperature	Sub-clause 4.19	-
		Lower category temperature:-55 °C	
		Upper category temperature:+155 °C	
		Duration of exposure at each temperature: 30	
		min.	
		Number of cycles: 5 cycles.	
		Visual examination	No visible damage
		Resistance	∆R≤±1%

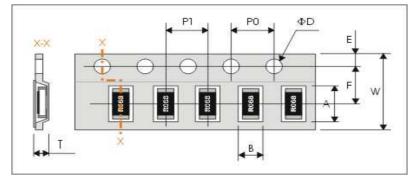
No	Test items	Condition of text (US C 5201 1)	Performance requirements
		Condition of test (JIS C 5201–1)	Penormance requirements
9	Climatic sequence	Sub-clause 4.23	
	–Dry heat	Sub-clause 4.23.2	
		Test temperature: +155 °C	
		Duration: 16 h	
	-Damp heat, cycle	Sub–clause 4.23.3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
	-Cold	Sub–clause 4.23.4	
		Test temperature –55 °C	
		Duration: 2h	
	–Damp heat, cycle	Sub–clause 4.23.6	
	(12+12hour cycle)	Test method: 2	
	Remaining cycle	Test temperature: 55 °C	
		[Severity (2)]	
		Number of cycles: 5 cycles	
	-D.C. load Sub-clause 4.23.7 The applied current shall be the rated current.		
		Duration: 1 min.	
		Visual examination	No visible damage
		Resistance	∆R≤±5%
10	Mounting	Sub-clause 4.31	2121370
10	Wounding	Substrate material: Epoxide woven glass	
		Test substrate: Figure-3	
		lesi substrate. Ligule=3	
	Endurance at 70 °C	Sub-clause 4.25.1	
		Ambient temperature: 70 °C±2 °C	
		Duration: 1000 h	
		The current shall be applied in cycles of 1.5 h	
		on and 0.5 h.	
		The applied current shall be the rated current	
		Examination at 48 h, 500 h and	
		1000 h:	
		Visual examination	
		Resistance	No visible damage
			∆R≤±3%
		1	

Table-4(3)

		Table4(4)	
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
11	Mounting	Sub–clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3	
	Variation of resistance with temperature	Sub–clause 4.8 +20 °C / +155 °C	As in Table–1
12	Mounting	Sub–clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3	
	Damp heat, steady state	Sub–clause 4.24 Ambient temperature: 60 ±2 °C Relative humidity: 93 ± ² ₃ % Without current applied. Visual examination Resistance	No visible damage Legible marking ∆ R ≤ ±1%
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table–4
	Mounting	Sub–clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3	
	Endurance at upper category temperature	Sub–clause 4.25.3 Ambient temperature:155 °C±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	No visible damage Δ R ≤ ±5%

PACKAGING

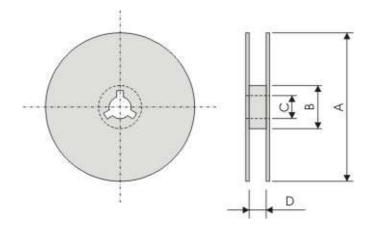
Plastic Tape specifications (unit :mm)



Symbol	Α	В	W	F	E
WW12D	3.60±0.20	2.00±0.15	8.00±0.20	3.50±0.05	1.75±0.10
WW08D	2.50±0.20	1.65±0.15	8.00±0.20	3.50±0.05	1.75±0.10

Symbol	P1	P0	ΦD	Т
WW12D	4.00±0.10	4.00±0.10	$\Phi 1.50^{+0.1}_{-0.0}$	1.0 max.
WW08D	4.00±0.10	4.00±0.10	$\Phi 1.50^{+0.1}_{-0.0}$	1.0 max.

Reel dimensions



Symbol	А	В	С	D
(unit : mm)	Ф180.0 -1.5	Φ60.0±1.0	13.0±0.2	9.0 +1.0

Taping quantity

- Chip resistors 5,000 pcs per reel.

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